



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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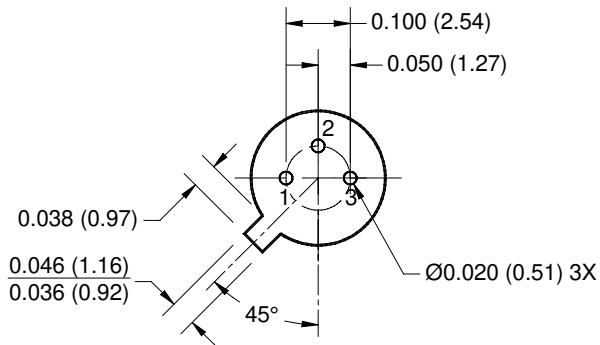
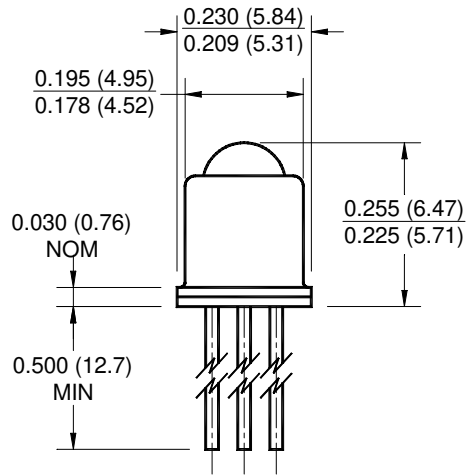
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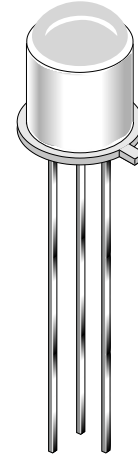


PACKAGE DIMENSIONS

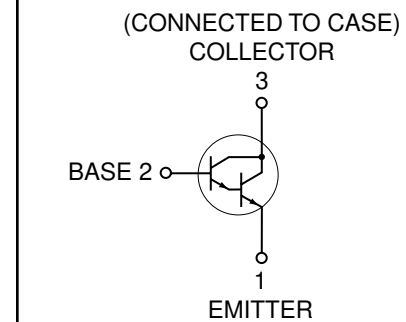


NOTES:

1. Dimensions for all drawings are in inches (mm).
2. Tolerance of $\pm .010 (.25)$ on all non-nominal dimensions unless otherwise specified.



SCHEMATIC



DESCRIPTION

The L14F1/L14F2 are silicon photodarlington mounted in a narrow angle, TO-18 package.

FEATURES

- Hermetically sealed package
- Narrow reception angle

L14F1 L14F2

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise specified)			
Parameter	Symbol	Rating	Unit
Operating Temperature	T_{OPR}	-65 to +125	$^\circ\text{C}$
Storage Temperature	T_{STG}	-65 to +150	$^\circ\text{C}$
Soldering Temperature (Iron) ^(3,4,5 and 6)	T_{SOL-I}	240 for 5 sec	$^\circ\text{C}$
Soldering Temperature (Flow) ^(3,4 and 6)	T_{SOL-F}	260 for 10 sec	$^\circ\text{C}$
Collector to Emitter Breakdown Voltage	V_{CEO}	25	V
Collector to Base Breakdown Voltage	V_{CBO}	25	V
Emitter to Base Breakdown Voltage	V_{EBO}	12	V
Power Dissipation ($T_A = 25^\circ\text{C}$) ⁽¹⁾	P_D	300	mW
Power Dissipation ($T_C = 25^\circ\text{C}$) ⁽²⁾	P_D	600	mW

NOTE:

1. Derate power dissipation linearly 3.00 mW/ $^\circ\text{C}$ above 25 $^\circ\text{C}$ ambient.
2. Derate power dissipation linearly 6.00 mW/ $^\circ\text{C}$ above 25 $^\circ\text{C}$ case.
3. RMA flux is recommended.
4. Methanol or isopropyl alcohols are recommended as cleaning agents.
5. Soldering iron tip 1/16" (1.6mm) minimum from housing.
6. As long as leads are not under any stress or spring tension.
7. Light source is a GaAs LED emitting light at a peak wavelength of 940 nm.
8. Figure 1 and figure 2 use light source of tungsten lamp at 2870 $^\circ\text{K}$ color temperature. A GaAs source of 0.05 mW/cm² is approximately equivalent to a tungsten source, at 2870 $^\circ\text{K}$, of 0.2 mW/cm².

ELECTRICAL / OPTICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$) (All measurements made under pulse conditions)						
PARAMETER	TEST CONDITIONS	SYMBOL	MIN	TYP	MAX	UNITS
Collector-Emitter Breakdown	$I_C = 10\text{ mA}, E_e = 0$	BV_{CEO}	25		—	V
Emitter-Base Breakdown	$I_E = 100\ \mu\text{A}, E_e = 0$	BV_{EBO}	12		—	V
Collector-Base Breakdown	$I_C = 100\ \mu\text{A}, E_e = 0$	BV_{CBO}	25		—	V
Collector-Emitter Leakage	$V_{CE} = 12\text{ V}, E_e = 0$	I_{CEO}	—		100	nA
Reception Angle at 1/2 Sensitivity		θ		± 8		Degrees
On-State Collector Current L14F1	$E_e = .125\text{ mW/cm}^2, V_{CE} = 5\text{ V}^{(7)}$	$I_{C(ON)}$	7.5		—	mA
On-State Collector Current L14F2	$E_e = .125\text{ mW/cm}^2, V_{CE} = 5\text{ V}^{(7)}$	$I_{C(ON)}$	2.5			mA
Rise Time	$I_C = 10\text{ mA}, V_{CC} = 5\text{ V}, R_L = 100\ \Omega$	t_r		300		μs
Fall Time	$I_C = 10\text{ mA}, V_{CC} = 5\text{ V}, R_L = 100\ \Omega$	t_f		250		μs

L14F1 L14F2

Figure 1. Light Current vs. Collector to Emitter Voltage

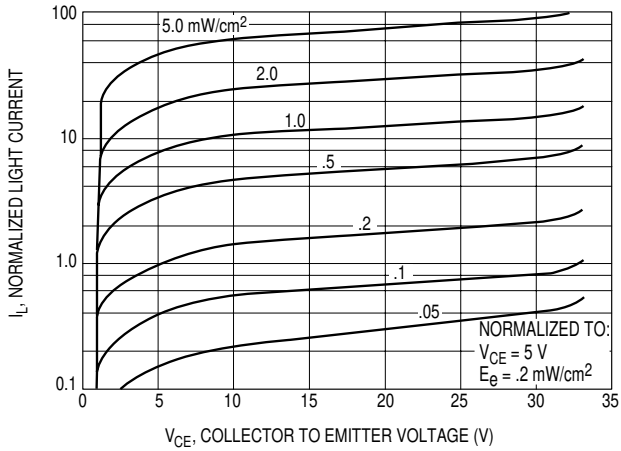


Figure 2. Relative Light Current vs. Ambient Temperature

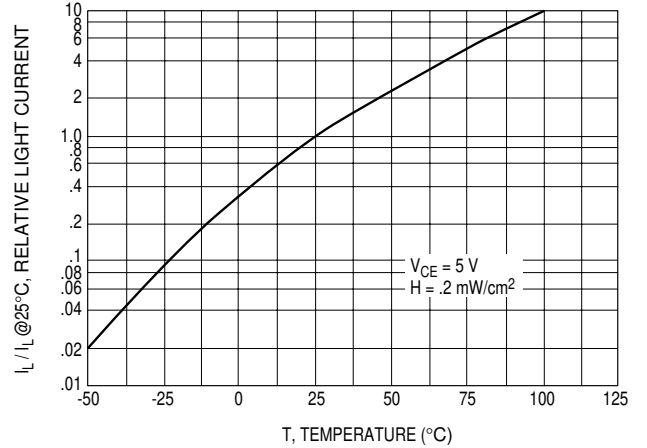


Figure 3. Spectral Response

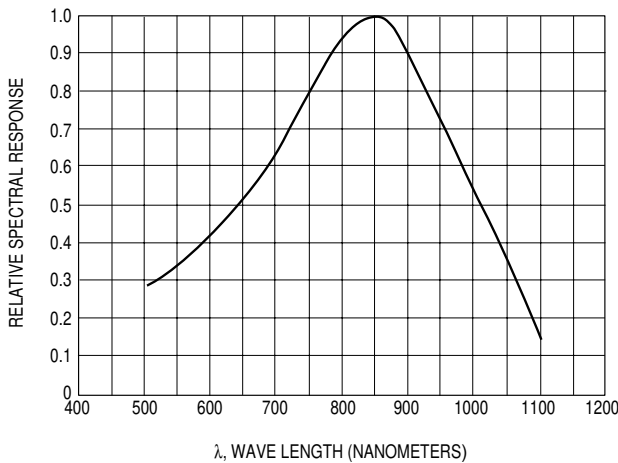


Figure 4. Angular Response

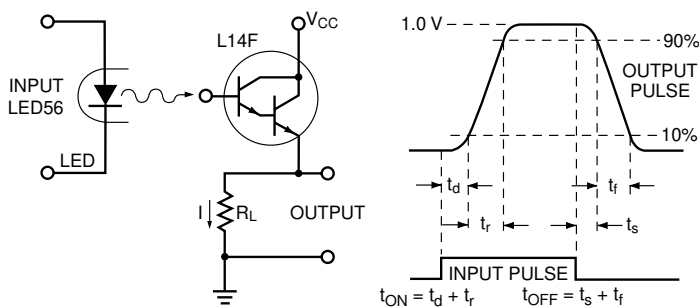
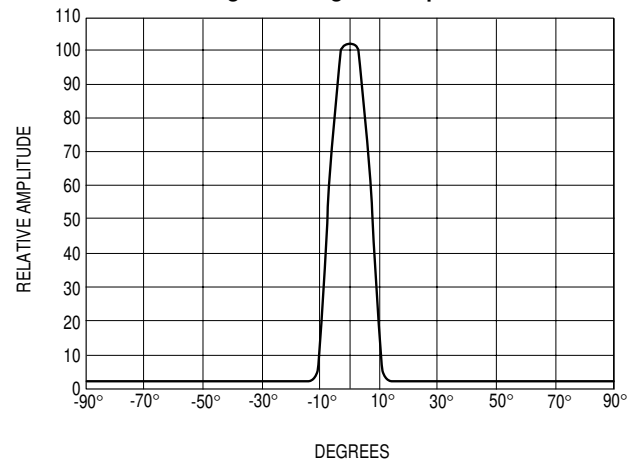
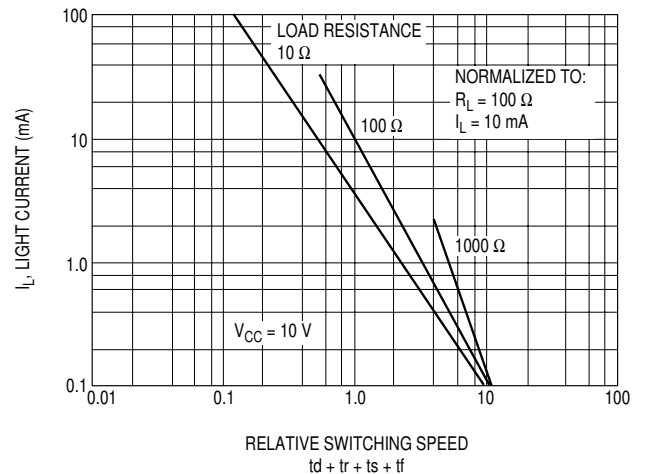


Figure 5. Test Circuit and Voltage Waveforms

Figure 6. Light Current vs. Relative Switching Speed



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